

LAMEA Advanced Packaging Market By Type (Flip-Chip Ball Grid Array, Flip Chip CSP, Wafer Level CSP, 2),5D/3D and others), By End User (Consumer Electronics, Automotive, Industrial, Aerospace & Defense, Healthcare & Life Sciences and Others), By Country, Industry Analysis and Forecast, 2020 - 2026

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Abstracts

The Latin America, Middle East and Africa Advanced Packaging Market would witness market growth of 14.9% CAGR during the forecast period (2020-2026).

Advanced packaging is a supportive case that avoids physical damage and degradation to silicon wafers, logic units and memory during the late stages of the semiconductor manufacturing process. Advanced packaging enables the chip to be connected to the circuit board. In addition, it involves the grouping of a variety of distinct techniques, including 2.5D, 3D-IC, fan-out-wafer-level packaging and system-in-packaging.

The increasing need for advanced wafer packaging techniques for fast-growing IoT and next-generation mobile chipsets is influencing the advanced packaging market. Growing demands for high-performance gadgets in developing economies have kept the market progressively lucrative over the years. Increasing the adoption of AI in industrial automation will increase the demand for high-end chips manufactured using advanced packaging. In the advanced packaging market, lithography manufacturing processes have accumulated steam. Furthermore, heterogeneous integration techniques are being used to gather steam between packaging service providers.

Advanced packaging in the semiconductor sector has observed a continuous transformation in terms of product characteristics, integration and energy efficiency.

This is due to a large demand across the various vertical end-users of the industry. Due to a variety of mainstream applications, including high-end smartphones and tablets, 2D integrated circuit (2.0DIC) flip-chip and wafer packaging technologies have experienced

significant growth over the years, which are expected to meet stringent size and power management requirements.

Based on Type, the market is segmented into Flip-Chip Ball Grid Array, Flip Chip CSP, Wafer Level CSP, 2.5D/3D and Others. Based on End User, the market is segmented into Consumer Electronics, Automotive, Industrial, Aerospace & Defense, Healthcare & Life Sciences and Others. Based on countries, the market is segmented into Brazil, Argentina, UAE, Saudi Arabia, South Africa, Nigeria, and Rest of LAMEA.

The market research report covers the analysis of key stake holders of the market. Key companies profiled in the report include Qualcomm, Inc., Intel Corporation, IBM Corporation, Texas Instruments, Inc., Analog Devices, Inc., Renesas Electronics Corporation, Samsung Electronics Co., Ltd. (Samsung Group), Amkor Technology, Inc., Brewer Science, Inc., and MICROCHIP Technology, Inc.

Scope of the Study

Market Segmentation:

By Type

Flip-Chip Ball Grid Array

Flip Chip CSP

Wafer Level CSP

2.5D/3D

Others

By End User

Consumer Electronics

Automotive

Industrial

Aerospace & Defense

Healthcare & Life Sciences

Others

By Country

Brazil

Argentina

UAE

Saudi Arabia

South Africa

Nigeria

Rest of LAMEA

Companies Profiled

Qualcomm, Inc.

Intel Corporation

IBM Corporation

Texas Instruments, Inc.

Analog Devices, Inc.

Renesas Electronics Corporation

Samsung Electronics Co., Ltd. (Samsung Group)

Amkor Technology, Inc.

Brewer Science, Inc.

Microchip Technology, Inc.

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